

## WHAT IS CLAIMED IS:

1. A pressure sensor including a semiconductor device capable of detecting a pressure, a terminal that is connected to the semiconductor device by a bonding wire, a housing having an accommodation space for accommodating the semiconductor device, bonding wire and the terminal, a diaphragm for sealing the accommodation space, working fluid that is sealed in the accommodation space, and transmits the pressure applied to the diaphragm to the semiconductor device, wherein

the working fluid is a silicone-based oil, and the terminal and the housing are sealed by a fluorine-based adhesive.

10

2. A pressure sensor including a semiconductor device that is capable of directly detecting a pressure, a terminal that is connected to the semiconductor device by a bonding wire, and a housing having an accommodation space for accommodating the semiconductor device, the bonding wire and the terminal, wherein

15

the terminal and the housing are sealed by a fluorine-based adhesive.

3. The pressure sensor according to claim 1, wherein the fluorine-based adhesive is a perfluoro polyether resin composition.

20

4. The pressure sensor according to claim 2, wherein the fluorine-based adhesive is a perfluoro polyether resin composition.